# DATA SHEET

# PHOTOCOUPLER PS2501-1,-2,-4,PS2501L-1,-2,-4

# HIGH ISOLATION VOLTAGE SINGLE TRANSISTOR TYPE MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

#### DESCRIPTION

The PS2501-1, -2, -4 and PS2501L-1, -2, -4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2501-1, -2, -4 are in a plastic DIP (Dual In-line Package) and the PS2501L-1, -2, -4 are lead bending type (Gull-wing) for surface mount.

#### **FEATURES**

- High isolation voltage (BV = 5 000 Vr.m.s.)
- High collector to emitter voltage (VCEO = 80 V)
- High-speed switching (tr = 3  $\mu$ s TYP., tr = 5  $\mu$ s TYP.)
- Ordering number of tape product: PS2501L-1-E3, E4, F3, F4, PS2501L-2-E3, E4
- Safety standards
  - UL approved: File No. E72422

#### **APPLICATIONS**

- Power supply
- Telephone/FAX.
- FA/OA equipment
- Programmable logic controller

# (Top View) PS2501-1, PS2501L-1

**PIN CONNECTION** 

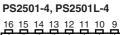


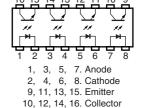


#### PS2501-2, PS2501L-2



1.3. Anode 2, 4. Cathode 5, 7. Emitter 6, 8. Collector

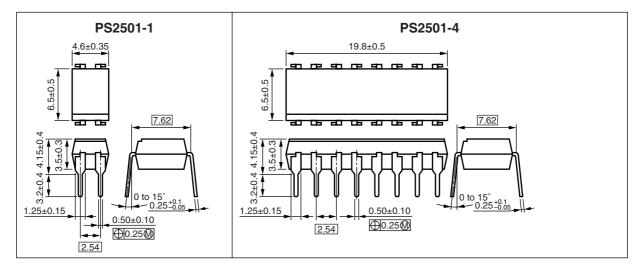




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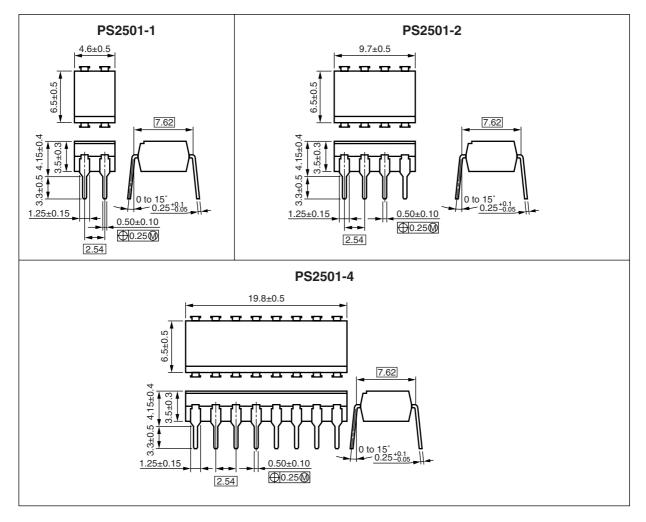
## PACKAGE DIMENSIONS (UNIT : mm)

# DIP Type (New package)



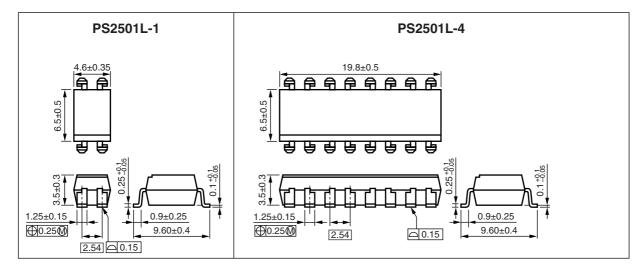
Caution New package 1-ch, 4-ch only





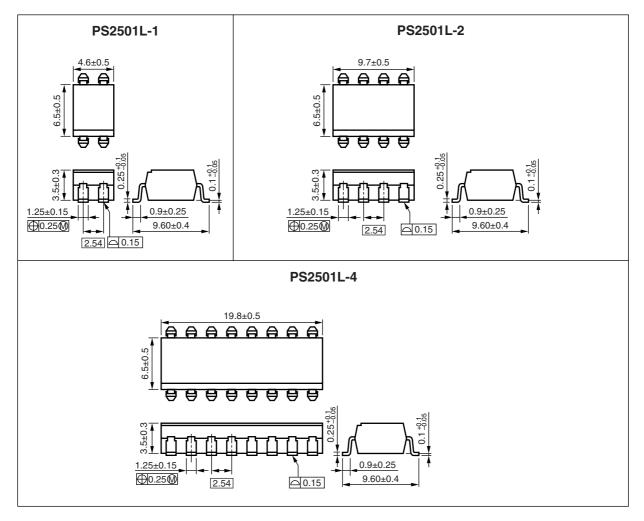
Data Sheet PN10225EJ02V0DS

## Lead Bending Type (New package)

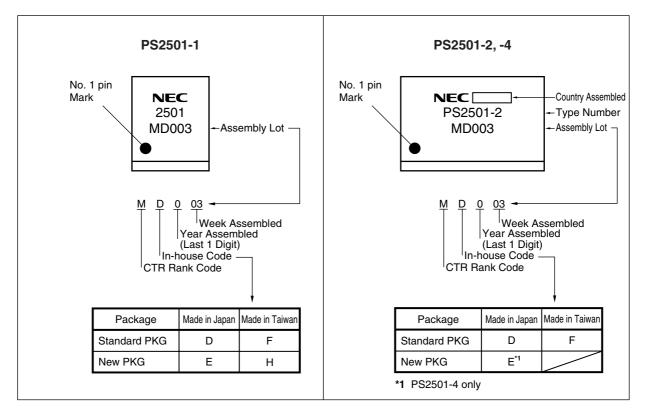


#### Caution New package 1-ch, 4-ch only

#### Lead Bending Type



#### MARKING EXAMPLE



## **\*** ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS2501-1	PS2501-1	Solder	Magazine case 100 pcs	Standard products	PS2501-1
PS2501L-1	PS2501L-1	contains lead		(UL Approved)	
PS2501L-1-E3	PS2501L-1-E3		Embossed Tape 1 000 pcs/reel		
PS2501L-1-E4	PS2501L-1-E4				
PS2501L-1-F3	PS2501L-1-F3		Embossed Tape 2 000 pcs/reel		
PS2501L-1-F4	PS2501L-1-F4				
PS2501-2	PS2501-2		Magazine case 45 pcs		PS2501-2
PS2501L-2	PS2501L-2				
PS2501L-2-E3	PS2501L-2-E3		Embossed Tape 1 000 pcs/reel		
PS2501L-2-E4	PS2501L-2-E4				
PS2501-4	PS2501-4		Magazine case 20 pcs		PS2501-4
PS2501L-4	PS2501L-4				
PS2501-1	PS2501-1-A	Pb-Free	Magazine case 100 pcs		PS2501-1
PS2501L-1	PS2501L-1-A				
PS2501L-1-E3	PS2501L-1-E3-A		Embossed Tape 1 000 pcs/reel		
PS2501L-1-E4	PS2501L-1-E4-A				
PS2501L-1-F3	PS2501L-1-F3-A		Embossed Tape 2 000 pcs/reel		
PS2501L-1-F4	PS2501L-1-F4-A				
PS2501-2	PS2501-2-A		Magazine case 45 pcs		PS2501-2
PS2501L-2	PS2501L-2-A				
PS2501L-2-E3	PS2501L-2-E3-A		Embossed Tape 1 000 pcs/reel	]	
PS2501L-2-E4	PS2501L-2-E4-A				
PS2501-4	PS2501-4-A		Magazine case 20 pcs		PS2501-4
PS2501L-4	PS2501L-4-A				

\*1 For the application of the Safety Standard, following part number should be used.

Parameter			Rat		
		Symbol	PS2501-1, PS2501L-1	PS2501-2,-4 PS2501L-2,-4	Unit
Diode	Reverse Voltage	VR	6		V
	Forward Current (DC)	lf	8	0	mA
	Power Dissipation Derating	⊿P₀/°C	1.5	1.2	mW/°C
	Power Dissipation	PD	150	120	mW/ch
	Peak Forward Current <sup>1</sup>	IFP		1	А
Transistor	Collector to Emitter Voltage	VCEO	8	0	V
	Emitter to Collector Voltage	VECO	-	7	V
	Collector Current	lc	5	0	mA/ch
	Power Dissipation Derating	⊿Pc/°C	1.5	1.2	mW/°C
	Power Dissipation	Pc	150	120	mW/ch
Isolation Voltage <sup>2</sup>		BV	5 000		Vr.m.s.
Operating Ambient Temperature		TA	-55 to +100		°C
Storage Temperature		Tstg	–55 to +150		°C

#### ABSOLUTE MAXIMUM RATINGS (Unless otherwise specified, T<sub>A</sub> = 25°C)

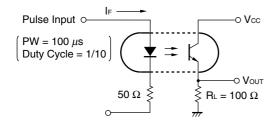
\*1 PW = 100 *µ*s, Duty Cycle = 1%

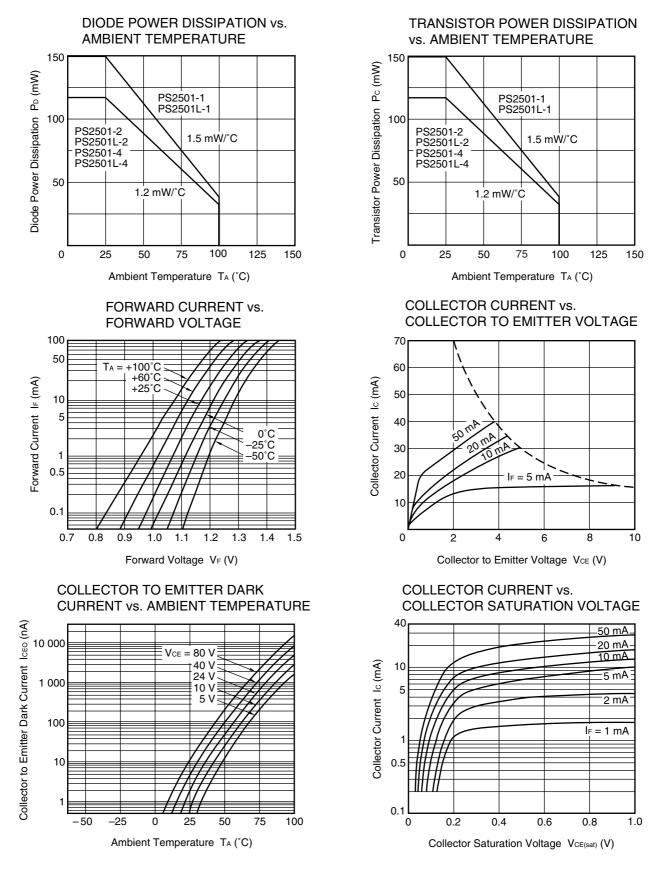
\*2 AC voltage for 1 minute at  $T_A = 25^{\circ}$ C, RH = 60% between input and output. Pins 1-2 shorted together, 3-4 shorted together (PS2501-1, PS2501L-1). Pins 1-4 shorted together, 5-8 shorted together (PS2501-2, PS2501L-2). Pins 1-8 shorted together, 9-16 shorted together (PS2501-4, PS2501L-4).

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.17	1.4	V
	Reverse Current	IR	$V_{R} = 5 V$			5	μA
	Terminal Capacitance	Ct	V = 0 V, f = 1.0 MHz		50		pF
Transistor	Collector to Emitter Dark Current	Iceo	$V_{CE} = 80 \text{ V}, \text{ IF} = 0 \text{ mA}$			100	nA
Coupled	Current Transfer Ratio (Ic/I⊧) <sup>*1</sup>	CTR	IF = 5 mA, VCE = 5 V	80	300	600	%
	Collector Saturation Voltage	VCE(sat)	I⊧ = 10 mA, lc = 2 mA			0.3	V
	Isolation Resistance	Rŀ-o	VI-O = 1.0 kVDC	10 <sup>11</sup>			Ω
	Isolation Capacitance	CI-0	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time <sup>*2</sup>	tr	$V_{CC}$ = 10 V, Ic = 2 mA, RL = 100 $\Omega$		3		μs
	Fall Time <sup>2</sup>	tr			5		

#### ELECTRICAL CHARACTERISTICS (TA = 25°C)

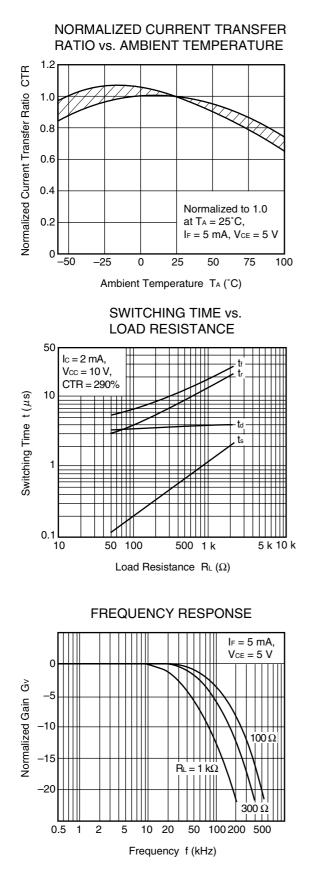
- \*1 CTR rank (\*: only PS2501-1, PS2501L-1)
  - K\* : 300 to 600 (%)
  - L\* : 200 to 400 (%)
  - M\*: 80 to 240 (%)
  - D\*: 100 to 300 (%)
  - H\* : 80 to 160 (%)
  - W\*: 130 to 260 (%)
  - Q\*: 100 to 200 (%)
  - N : 80 to 600 (%)
- \*2 Test circuit for switching time

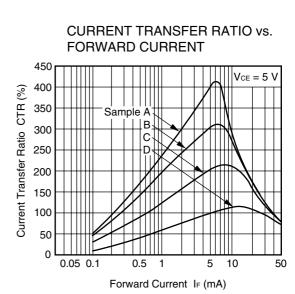




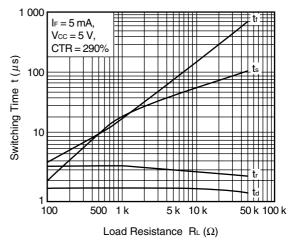


Remark The graphs indicate nominal characteristics.

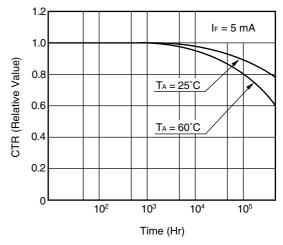




SWITCHING TIME vs. LOAD RESISTANCE

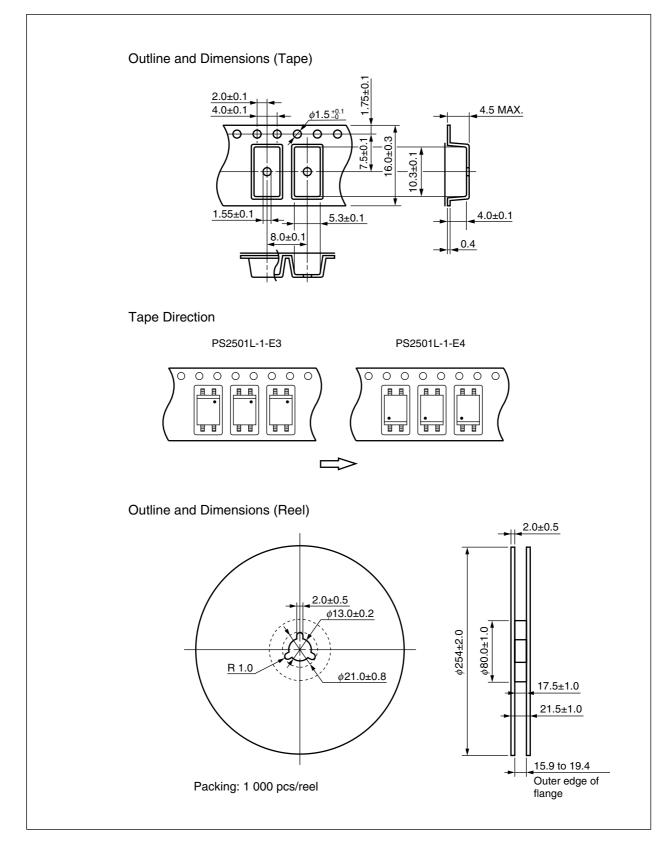


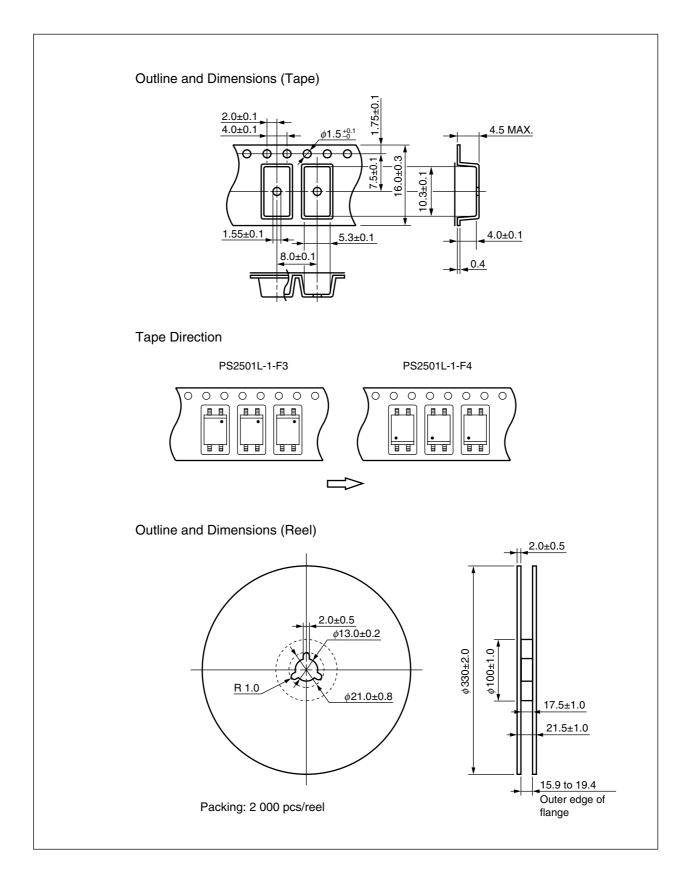
LONG TERM CTR DEGRADATION

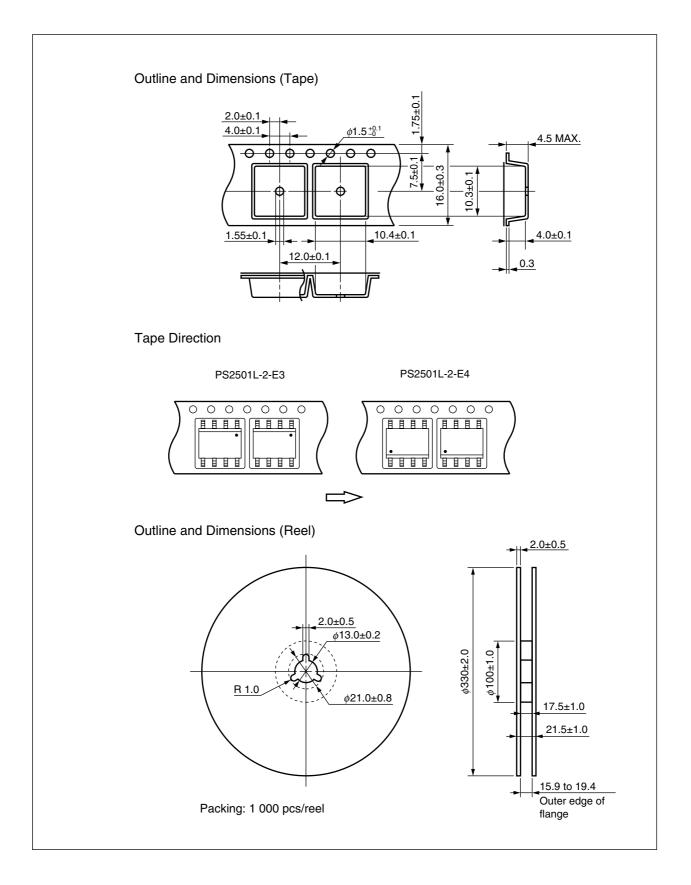


**Remark** The graphs indicate nominal characteristics.

### TAPING SPECIFICATIONS (UNIT : mm)







### **\*** NOTES ON HANDLING

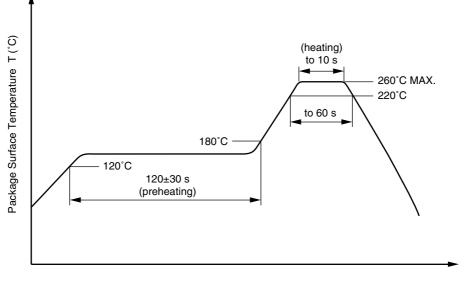
#### 1. Recommended soldering conditions

#### (1) Infrared reflow soldering

- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### Recommended Temperature Profile of Infrared Reflow



Time (s)

#### (2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### (3) Soldering by soldering iron

Peak temperature (lead part temperature)	350°C or below
<ul> <li>Time (each pins)</li> </ul>	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a
	maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

#### (4) Cautions

### • Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

#### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

### **USAGE CAUTIONS**

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 00.4-0110

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	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	<ol> <li>Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> </ol>
	<ol><li>Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li></ol>
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	<ul> <li>Do not lick the product or in any way allow it to enter the mouth.</li> </ul>

► For further information, please contact

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